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Double Excellence: KONIG's KP400 Wins Two Top Honors at NEPCON Asia

Shenzhen, China — November 2025 — KONIG, a leader in electronic packaging protection solutions, received two major awards on the opening day of NEPCON Asia for its breakthrough 3D Digital Packaging Equipment KP400. The 19th Step-by-Step Excellence Awards (SbSEA), one of China's top recognitions in electronics manufacturing, were announced on October 28. KONIG's system earned both the SbS China Achievement Award and the SbS Innovation Award, recognizing its leading contribution to China's electronics manufacturing sector.



A New Standard in Electronic Packaging

The KP400 represents a major step forward in digital packaging. Designed for mask-free precision coating, it replaces traditional coating, dispensing, and potting methods with a more accurate,

flexible approach. By combining the best aspects of planar inkjet and 3D printing technologies, the KP400 moves packaging protection from a flat process to a fully digital, three-dimensional solution.

With over 1,000 independently controlled nozzles operating at up to 20,000 drops per second, the KP400 achieves picoliter-level control for selective, gapless, and bubble-free coverage. Its advanced image processing and precision jetting deliver a 0.2 mm safety distance without masking and can build 3D protective structures for PCBA, FPC, and Mini-LED products.



Designed to Solve Real Manufacturing Challenges

"We are committed to the field of electronic product packaging protection, always aiming to solve the real pain points in packaging, allowing innovative technologies to bring new value and truly serve the entire electronic manufacturing industry chain," said Jason Zhu (Jianxiao Zhu), CEO of KÖNIG.

The KP400 simplifies the coating process from multiple steps into just four: load, coat, cure, unload. This streamlined process completes thin-layer coating in as little as two seconds per board, improving throughput and reducing cycle time.

Smarter, Faster, More Reliable

- **Lower Costs:** By eliminating masking materials and jigs, manufacturers save significantly on labor and consumables. One customer reported annual cost savings of more than **50%** after switching to the KP400.
- **Better Yields:** Precise jetting and instant UV LED curing prevent glue flow and coverage issues, producing cleaner edges and more stable results.
- **Stronger Reliability:** KÖNIG's 3D protective structures have passed demanding tests, including temperature shock, humidity, salt spray, and water immersion, proving long-term durability.
- **Safer Operation and Greener Production:** With no manual masking or demasking, operators have less chemical exposure. The precise glue control also reduces material waste, energy use, and industrial emissions.

Helping Manufacturers Move Forward

More than 50 companies across industrial, consumer, and automotive electronics are already using the KP400 to upgrade their packaging processes. The system has helped customers double production capacity, improve yields, and replace imported equipment with homegrown innovation. The success of the KP400 reflects KONIG's focus on creating practical, forward-thinking solutions that help manufacturers produce better, more reliable products.

To learn more about the KP400 Conformal Coating System, visit <http://konig.hk/en.asp> or contact info@konig.hk.

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About KONIG

Founded in 2010, KONIG is a national-level "Specialized, Refined, Unique, and Innovative" enterprise dedicated to electronic product packaging protection. The company develops low-pressure injection molding and digital packaging technologies that combine performance, reliability, and environmental responsibility.

KONIG is certified to ISO9001, IATF16949, ISO14001, ISO13485, DUNS, and CE, and serves customers across the SMT, semiconductor, consumer electronics, and automotive industries. From new energy vehicles to advanced medical devices, KONIG helps manufacturers build the next generation of high-quality electronic products.